

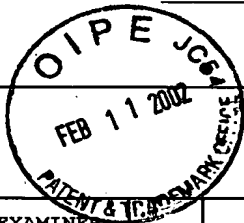
Sheet 1 of 1

Atty. Docket No.  
4172Serial No.:  
10/016,495LIST OF REFERENCES CITED BY  
APPLICANT

(REVISED FORM PTO-1449)

DATED: January 30, 2002

Applicant: Klaus SAUTER et al.

U.S. Filing Date:  
October 30, 2001Art Unit:  
2811

## U. S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	Cl.	Sub- Cl.	Fil. Date
TT	AA	4 2 9 5 1 1 7	10/1981	Lake et al.	-	-	-
TT	AB	4 5 4 5 8 4 0	10/1985	Newman et al.	-	-	-

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.							DATE	COUNTRY	Cl.	Sub- Cl.	Trans.	
													Yes	No
TT	AC	2	7	5	6	5	0	0	06/1979	Fed. Rep. of Germany	-	-		x
TT	AD	60	2	5	3	2	8	0	12/1985	Japan (English Abstract)	-	-	x Abst.	
TT	AE	G9	1	1	6	2	0	6	05/1992	Germany (Utility Model)	-	-		x
TT	AF	WO 97	/	2	2	9	9	3	06/1997	PCT	-	-	x	

## OTHER DOCUMENTS

TT	AG	IBM Technical Disclosure Bulletin, "Chip-Heatsink Attach Using Contoured Adhesive With Glass Stand-Offs"; IBM Technical Disclosure Bulletin Vol. 34, No. 3; August 1, 1991; IBM Corporation, New York, 238,761,162.												
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EXAMINER

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DATE CONSIDERED

06-13-03

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.